GIGABYTE™

G4L4-SD3-LAX7

HPC/AI Server - Intel® Xeon® 6700/6500-Series Processors - 4U DP NVIDIA HGX™ B300 DLC

Key Features

- Liquid-cooled NVIDIA HGX™ B300
- Integrated-manifold DLC solution with leak detection
- 8 x 800 Gb/s OSFP XDR InfiniBand or dual 400 Gb/s Ethernet GPU networking ports via onboard NVIDIA ConnectX®-8 SuperNIC™
- 1.8 TB/s GPU-to-GPU bandwidth with NVIDIA NVLink™
- Dual Intel® Xeon® 6700/6500-Series Processors
- 8-Channel liquid-cooled DDR5 RDIMM/MRDIMM per CPU with 32 x DIMMs
- Compatible with NVIDIA BlueField®-3 DPUs
- 2 x 10 Gb/s LAN ports via Intel® X710-AT2
- 2 x M.2 slots with PCIe Gen5 x4 and x2
- 8 x 2.5" Gen5 NVMe hot-swap bays
- 4 x FHHL PCIe x16 slots with Gen5 x16 lanes
- 5+5 3000 W 80 PLUS Titanium redundant power supplies

Specification

Dimensions	4U (W447 x H175.5 x D901 mm)
Motherboard	MSB4-PE3
CPU	Intel® Xeon® 6 Processors - Intel® Xeon® 6700-Series Processors - Intel® Xeon® 6500-Series Processors [DLC] Dual processors, TDP up to 350 W
OS Compatibility	OS Support List
Socket	2 x LGA 4710 (Socket E2)
Chipset	System on Chip
Memory	[DLC] 8-Channel DDR5 RDIMM/MRDIMM, 32 x DIMMs [RDIMM] Up to 6400 MT/s (1DPC), 6000 MT/s (2DPC) [MRDIMM] Up to 8000 MT/s [1] [1] MRDIMMs are supported only on select Intel® Xeon® 6 processors with P-cores and only in a 1DPC configuration.
LAN	**Front:** 2 x 10 Gb/s LAN (1 x Intel® X710-AT2), Support NCSI 1 x 10/100/1000 Mb/s Management LAN **Rear:** [DLC] 8 x 800 Gb/s OSFP XDR InfiniBand or dual 400 Gb/s Ethernet, for GPU networking 1 x 10/100/1000 Mb/s Management LAN
Video	Integrated in ASPEED® AST2600 - 1 x VGA port
Storage	**Front hot-swap:** 8 x 2.5" Gen5 NVMe **Internal M.2:** 1 x M.2 (2280/22110), PCIe Gen5 x4 1 x M.2 (2280/22110), PCIe Gen5 x2
Modular GPU	[DLC] NVIDIA HGX™ B300 with 8 x SXM GPUs
PCIe Expansion Slots	4 x FHHL x16 (Gen5 x16) *The ambient temperature is limited to 30°C when NVIDIA BlueField®-3 DPUs/SuperNIC™ are installed.
I/O Ports	**Front:** 2 x USB 3.2 Gen1, 1 x VGA, 2 x RJ45, 1 x MLAN (default) **Rear:** 1 x MLAN
TPM	1 x TPM header (SPI), Optional TPM 2.0 kit: CTM012
Power Supply	5+5 3000 W 80 PLUS Titanium redundant power supplies AC Input: 115V-240 V *The system power supply requires C19 power cord.
System Fans	Motherboard: 2 x 60x60x38mm 3 x 60x60x56mm PCIe slots: 2 x 80x80x56mm
Operating Properties	Operating: 10°C to 35°C, 8% to 80% (non-condensing) Non-operating: -40°C to 60°C, 20% to 95% (non-condensing) *To ensure system stability and prevent condensation, when the relative humidity exceeds 50%, the coolant inlet temperature must be higher than the dry-bulb temperature and it should not exceed 45°C.
Packaging Content	1 x G4L4-SD3-LAX7 4 x Carriers 1 x L-shape Rail kit
Ordering Part Numbers	6NG4L4SD3DR000LAX7*

Learn more at: https://www.gigabyte.com/Enterprise

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